



【 3. 定格 RATINGS 】

項 目 Item	規 格 Standard	
最大許容電圧 Rated Voltage (MAX.)	125 V <sup>*3</sup>	[AC (実効値 rms) /DC]
最大許容電流 Rated Current (MAX.)	2.0 A <sup>*3</sup>	
使用温度範囲 <sup>*1</sup> Ambient Temperature Range	-40°C ~ +125°C <sup>*2*3</sup>	
保管条件 Storage Condition	温度 Temperature	-10°C~+50°C
	湿度 Humidity	45~80%R.H.以下 (但し結露しないこと) 45~80%R.H. MAX. (No Condensation)
	期間 Terms	出荷後12ヶ月 (未開封の場合) For 12 months after shipping (unopened package)

\*1: 基板実装後の無通電状態は、使用温度範囲を適用する。

Non-operating connectors after reflow must follow the operating temperature range condition.

\*2: 通電による温度上昇分を含む。

This includes the terminal temperature rise generated by conducting electricity.

\*3: 適合FPC(電線、ケーブル等)も本定格を満足すること。

Applicable FPC (wires and cables) must also meet the specified in this standard.

REVISE ON PC ONLY		TITLE: 2.0 mm PITCH FPC TO BOARD CONNECTOR		
<b>D</b>	SEE SHEET 1 OF 19	<b>製品仕様書</b>		
REV.	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
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【4. 性能 PERFORMANCE】

4-1. 電気的性能 Electrical Performance

項目 Item	条件 Test Condition	規格 Requirement
4-1-1 接触抵抗 Contact Resistance	適合FPCコネクタを嵌合させ、開放電圧 20mV 以下、短絡電流 10mA 以下にて測定する。 (JIS C5402-2-1)  Mate applicable FPC connector, measured at the open circuit voltage 20mV MAXIMUM and short circuit 10mA MAXIMUM.(JIS C5402-2-1)	40 milliohm MAX.
4-1-2 絶縁抵抗 Insulation Resistance	適合FPCコネクタを嵌合させ、隣接するターミナル間及びターミナル、アース間に、DC 500Vを印加し測定する。 (JIS C5402-3-1/MIL-STD-202 試験法 302)  Mate applicable FPC connector, measured by applying DC 500V between adjacent terminal or terminal and ground. (JIS C5402-3-1/MIL-STD-202 Method 302)	50 megaohm MIN.
4-1-3 耐電圧 Dielectric Strength	適合FPCコネクタを嵌合させ、隣接するターミナル間及びターミナル、アース間に、AC1000V（実効値）を1分間印加する。 (JIS C5402-4-1/MIL-STD-202 試験法 301)  Mate applicable FPC connector, applying AC 1000V (effective value) between adjacent terminal or terminal and ground for 1 minutes. (JIS C5402-4-1/MIL-STD-202 Method 301)	異状なきこと No Breakdown

4-2. 機械的性能 Mechanical Performance

項目 Item	条件 Test Condition	規格 Requirement
4-2-1 挿入・抜去力 Insertion Force/ Withdrawal Force	ロックを解除した状態にて、毎分 25±3 mm の速さで挿入・抜去を行う。  Insert and withdraw connectors, at the speed rate of 25+/-3 mm per minute.	挿入力 Insertion Force 20.0N {2.0 kgf} MAX. 抜去力 Withdrawal Force 20.0N {2.0 kgf} MAX.
4-2-1 強制抜去力 Compulsion Withdrawal Force	適合FPCコネクタを嵌合させ、ロックを解除せずに毎分 25±3 mm の速さで軸方向に引き抜く。  Mate applicable FPC connector, apply axial pull out force at the speed rate of 25+/-3 mm per minute.	20.0 N{2.0 kgf} MIN.

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4-3. その他 Environmental Performance and Others

項目 Item		条件 Test Condition	規格 Requirement	
4-3-1	繰り返し挿抜 Repeated Mate / Un-mate	無通電状態にて、1分間に 10回以下の速さで挿入、抜去を 20回 繰り返す。 When mated up to 20 cycles repeatedly at the speed rate of less than 10 cycles per minute.	接触抵抗 Contact Resistance	60 milliohm MAX.
4-3-2	温度上昇 Temperature Rise	適合FPCコネクタを嵌合させ、最大許容電流を通電し、コネクタの温度上昇分を測定する。 (UL 498) Mate applicable FPC connector, measure the temperature rise of contact when the maximum AC rated current is passed.(UL 498)	温度上昇 Temperature Rise	30 °C MAX.
4-3-3	耐振動性 Vibration	適合FPCコネクタを嵌合させ、DC1mA通電状態にて、嵌合軸を含む互いに垂直な3方向に掃引割合 20~200~20 Hz/3分、加速度88m/s <sup>2</sup> の振動を3時間加える。 Mate applicable FPC connector, add to 3 hours with ratio sweep 20-200-20 Hz per 3 minutes and acceleration of 88m/s <sup>2</sup> at 3 directions mutually vertical including fitting axis in DC 1 mA electricity state.	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	60 milliohm MAX.
			瞬断 Discontinuity	1 microsecond MAX
4-3-4	耐衝撃性 Shock	適合FPCコネクタを嵌合させ、DC 1mA通電状態にて、嵌合軸を含む互いに垂直な 6方向に、981m/s <sup>2</sup> {100G}の衝撃を作用時間 6ミリ秒で各3回 加える。 (JIS C60068-2-27 / MIL-STD-202試験法 213) Mate applicable FPC connector, add to each 3 times with impact of 981m/s <sup>2</sup> {100G}on action time 6 milliseconds at 6 directions mutually vertical including fitting axis in DC 1 mA electricity state. (JIS C60068-2-27 / MIL-STD-202Method 213)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	60 milliohm MAX.
			瞬断 Discontinuity	1 microsecond MAX.

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項目 Item		条件 Test Condition	規格 Requirement	
4-3-5	耐熱性 Heat Resistance	適合FPCコネクタを嵌合させ、140±2℃の雰囲気中に120時間放置する。試験後、1～2時間室温に放置する。 (JIS C60068-2-2/MIL-STD-202 試験法 108)  Mate applicable FPC connector, exposing for 140 hours in the atmosphere of 140+/-2 degree C. After the test, allowed to stand at room temperature for 1 to 2 hours. (JIS C60068-2-2/MIL-STD-202 Method 108)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	60 milliohm MAX.
4-3-6	耐寒性 Cold Resistance	適合FPCコネクタを嵌合させ、-40±3℃の雰囲気中に120時間放置する。試験後、1～2時間室温に放置する。 ( JIS C60068-2-1 )  Mate applicable FPC connector and expose to -40+/-3 degree C for 120 hours. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours. ( JIS C60068-2-1 )	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	60 milliohm MAX.
4-3-7	耐湿性 Humidity	適合FPCコネクタを嵌合させ、60±2℃ 相対湿度 90～95% の雰囲気中に1000時間放置する。試験後、1～2時間室温に放置する。 (JIS C60068-2-78/MIL-STD-202 試験方法103)  Mate applicable FPC connector, exposing for 1000 hours in an atmosphere of 60+/-2 degree C, relative humidity 90 to 95%. After the test, allowed to stand at room temperature for 1 to 2 hours. (JIS C60068-2-78/MIL-STD-202 Method 103)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	60 milliohm MAX.
			耐電圧 Dielectric Strength	4-1-3項満足のこと Must meet 4-1-3
			絶縁抵抗 Insulation Resistance	20 megaohm MIN.

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項目 Item		条件 Test Condition	規格 Requirement	
4-3-8	温度サイクル Temperature Cycling	適合FPCコネクタを嵌合させ、-40±3℃に30分、+100±2℃に30分、これを1サイクルとし、1000サイクル繰り返す。但し、温度移行時間は、5分以内とする。試験後、1～2時間室温に放置する。 (JIS C60068-2-14)  Mate applicable FPC connector, exposing to 100+/-2 degree C and -40+/-3 degree C temperature extremes for 30 minutes each including a 0-5 minutes transition time. The above-mentioned condition is repeated 1000 cycles. After the test, allowed to stand at the room temperature for 1 to 2 hours before checking functionality. (JIS C60068-2-14)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	60 milliohm MAX.
4-3-9	塩水噴霧 Salt Spray	適合FPCコネクタを嵌合させ、35±2℃にて、重量比 5±1% の塩水を48時間噴霧し、試験後常温で水洗いした後、室温で乾燥させる。 (JIS C60068-2-11/MIL-STD-202 試験方法101) Mate applicable FPC connector, exposing to the atmosphere where salt mist is diffused in. Other condition is written below. NaCl solution : 5+/-1% by weight Temperature : 35+/-2 degree C Duration : 48 hours After the test, they should be washed well by water and dried at room temperature before checking functionality. (JIS C60068-2-11/MIL-STD-202 Method 101)	外観 Appearance	割れ、著しい腐食等 異常なきこと No Damage
			接触抵抗 Contact Resistance	60 milliohm MAX.
4-3-10	亜硫酸ガス SO <sub>2</sub> Gas	適合FPCコネクタを嵌合させ、25±2℃、湿度75%以上、25±5ppm の亜硫酸ガス中に96時間放置する。 Mate applicable FPC connector, exposing to the atmosphere is written below. Gas Concentration : SO <sub>2</sub> =25+/-5ppm Temperature : 25+/-2 degree C Humidity : 75% minimum Duration : 96h	接触抵抗 Contact Resistance	60 milliohm MAX.

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項目 Item		条件 Test Condition	規格 Requirement	
4-3-11	耐アンモニア性 NH <sub>3</sub> Gas	適合FPCコネクタを嵌合させ、濃度 28% のアンモニア水を入れた容器中に40分間放置する。  (1Lに対して25mLの割合) Mate applicable FPC connector, 40 minutes exposure to NH <sub>3</sub> gas evaporating from 28% Ammonia solution.	接触抵抗 Contact Resistance	60 milliohm MAX.
4-3-12	半田付け性 Solder Ability	端子先端より0.2mm、金具先端より0.2mmの位置まで、245±5°Cのはんだに3±0.5秒浸す。  Dip the position of mm from terminal tip and 0.2mm from fitting nail tip into 245 +/-5 degree C solder for 3+/-0.5 seconds.	濡れ性 Solder Wetting	浸漬面積の75%以上 75% of immersed area must show no voids, pin holes.
4-3-13	半田耐熱性 Resistance to Soldering Heat	赤外線リフロー時 Infrared Reflow Method 第7項参照 2回リフロー実施 Refer to the paragraph 7 2 times reflow enforcement	外観 Appearance	端子ガタ、割れ等 異状無き事 No Damage
		手半田時 Soldering iron method 端子先端より0.2mm、金具先端より0.2mmの位置まで350±10°Cのはんだゴテにて5秒加熱する。 但し、異常な加圧のないこと。 Heat the position of 0.2mm from terminal tip and 0.2mm from fitting nail tip for 5 seconds with 350+/-10 degree C soldering iron. However, without too much pressure to the terminal pin and fitting nail.		

( ) : 参考規格 Reference Standard  
{ } : 参考単位 Reference Unit

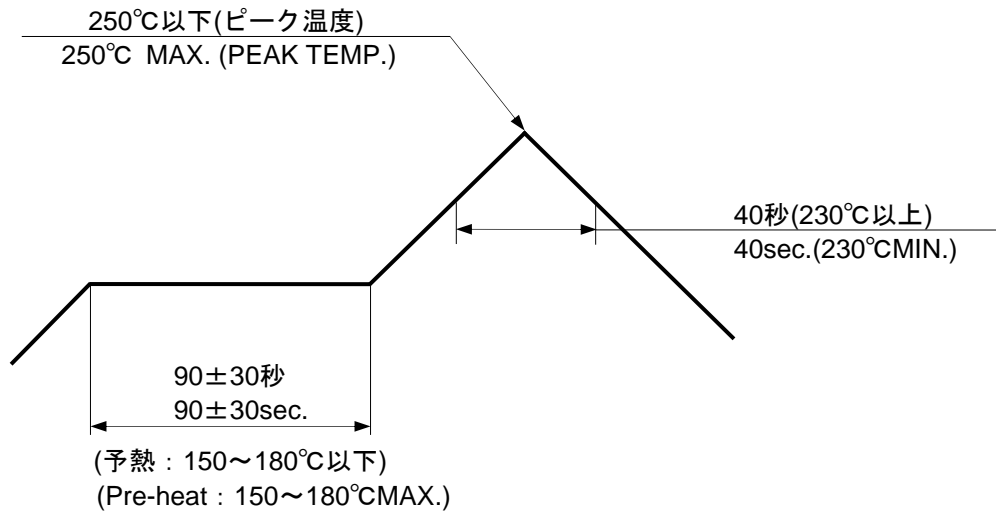
各項目の評価サンプルは、第7項のリフロー条件にて実装しております。  
また、半田ペーストは、無鉛半田 (Sn-3Ag-0.5Cu) を使用しております。  
The board samples of the specification test were reflowed under the reflow profile of paragraph 7.  
Cream soldering paste : Sn-3Ag-0.5Cu

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【5. 外観形状、寸法及び材質 PRODUCT SHAPE, DIMENSIONS AND MATERIALS】

図面参照 Refer to the drawing.

【6. 赤外線リフロー条件 INFRARED REFLOW CONDITION】



温度条件グラフ  
(温度は基板パターン面)

TEMPERATURE CONDITION GRAPH  
(TEMPERATURE ON THE SURFACE OF P.C.BOARD PATTERN)

注記 ; 本リフロー条件に関しては、リフロー装置及び基板などにより条件が異なりますので、事前にリフロー評価の確認をお願い致します。

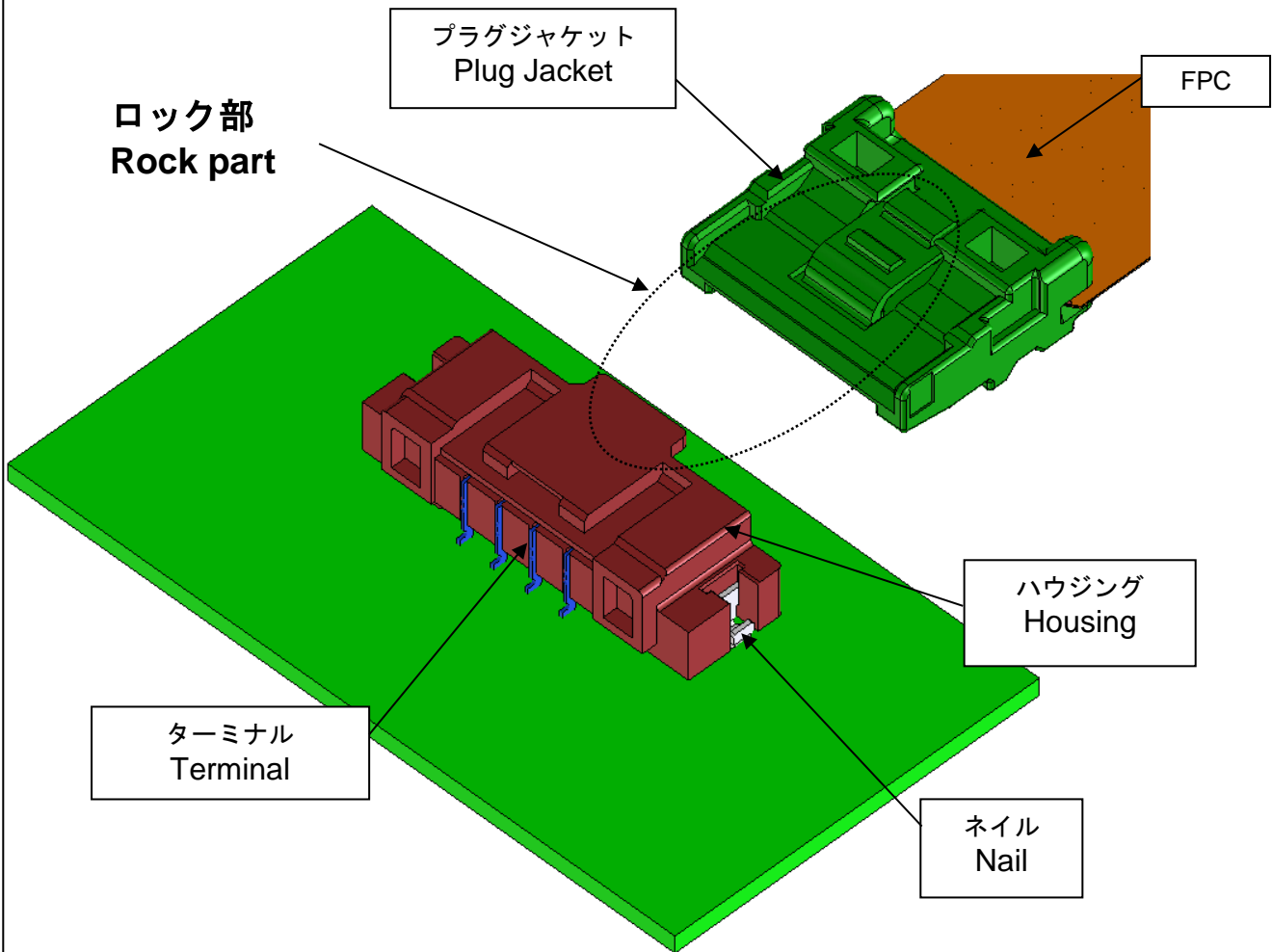
NOTE ; Please check the reflow soldering condition by your own devices beforehand. Because the condition changes by the soldering devices, P.C.Boards, and so on.

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【7. 取り扱い説明書 INSTRUCTION FOR THE HANDLING OF THE CONNECTOR】

7-1. 各部の名称 DESCRIPTION OF EACH PART



7-2. 基板への実装に関して MOUNTING ON THE PC BOARD

基板への実装は実装機にて実施願います。もし、半田ごてで実装する場合は、ターミナル及びネイルに触れない様に願います。（半田付け不良等の原因となる可能性が有ります。）

The mounting of the PC board is handled by the mouter. If to manually solder, please be cautious to not touch the Terminal and Fitting Nail.(It will create the possibility to cause solderbility failure.)

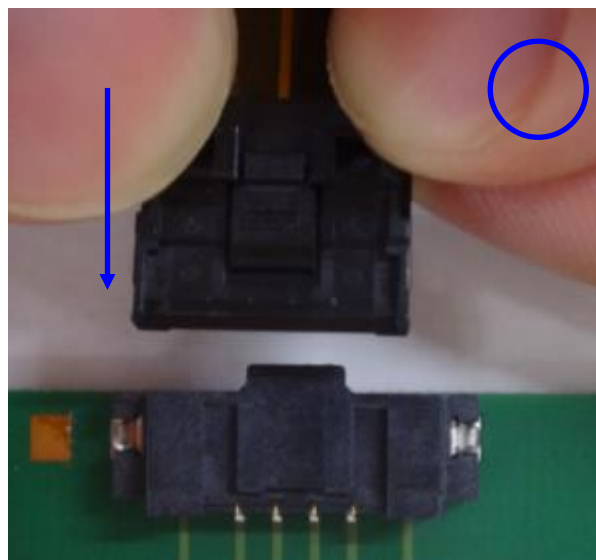
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7-3. コネクタ嵌合に関して MATING THE CONNECTOR

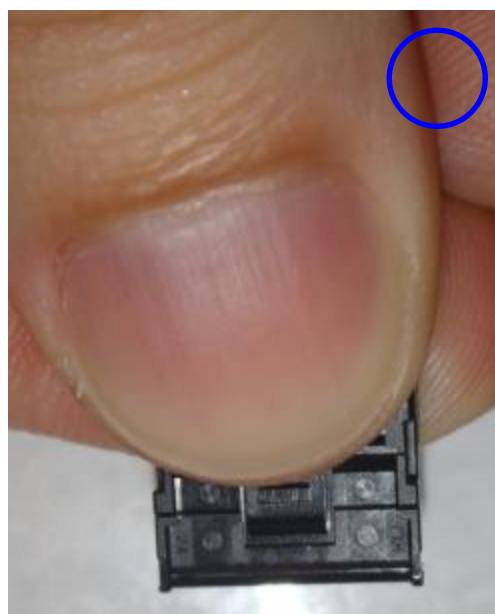
コネクタを嵌合する際は、プラグジャケットの全体もしくは中央を掴んで挿入を実施して下さい。

When mating the connector, hold the plug jacket at either a whole or the center portion of them to insert.

**全体  
WHOLE**



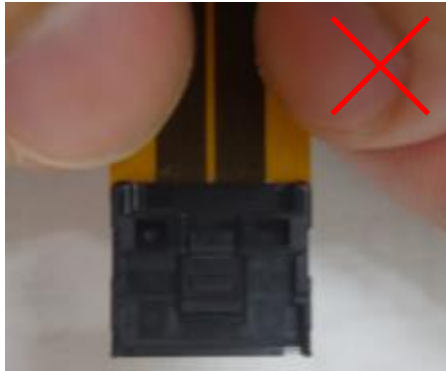
**中央  
CENTER**



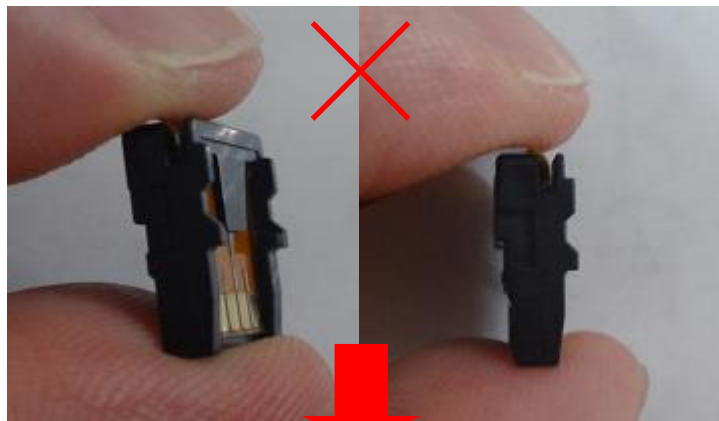
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以下のような嵌合は回復不可能な機能不全や製品破壊につながりますので実施しないで下さい。  
 The following method of mating will cause either irreversable functionality failure or product breaking, so please do not mate this way.

- ・ FPCのみを掴まないで下さい。  
 Please do not hold the FPC part only



- ・ 極数が多いとき、FPCを折り曲げるように掴まないで下さい。  
 When there are a lot of circuits. Please do not hold the FPC like bending it.



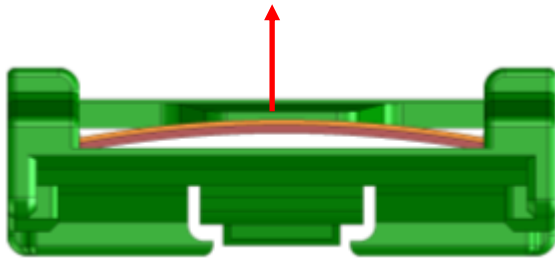
**FPCの浮き発生  
 WARPED FPC**



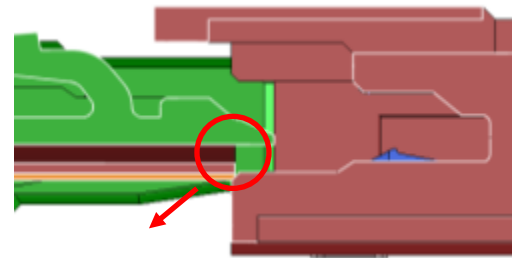
<b>D</b>	REVISE ON PC ONLY	TITLE: 2.0 mm PITCH FPC TO BOARD CONNECTOR			
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- ※ 極数が多いとき、FPCが極端に浮くと、嵌合時にハウジングと干渉し座屈する可能性があります。
- ※ When there are a lot of circuits.If FPC warps too much, it will touch with the Header housing when mated, and may possibly cause buckling.

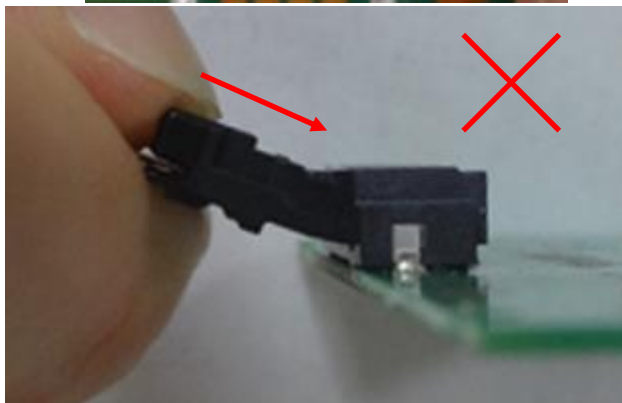
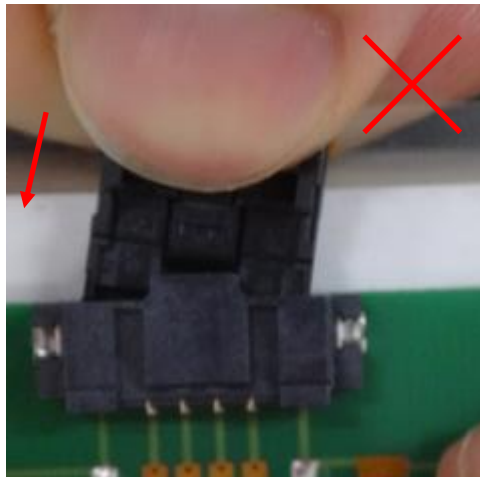
FPCの極端な浮き  
TO WARPED FPC



干渉  
TOUCH

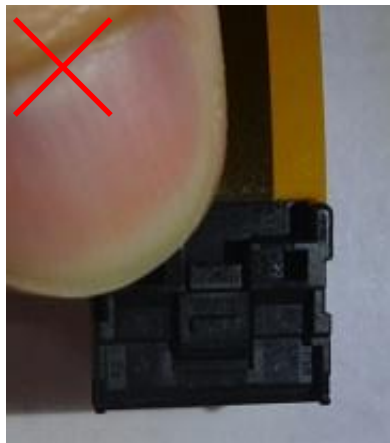


- ・斜め嵌合は不良につながりますので実施しないで下さい。  
Mating inconsistently will cause failure, so please do not do this.



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- ・プラグジャケットの片端のみを掴まないで下さい。斜め嵌合となり、不良につながります。  
Please do not hold one side of the plug jacket only as shown below.  
It will be mated in the slant direction and will cause failure

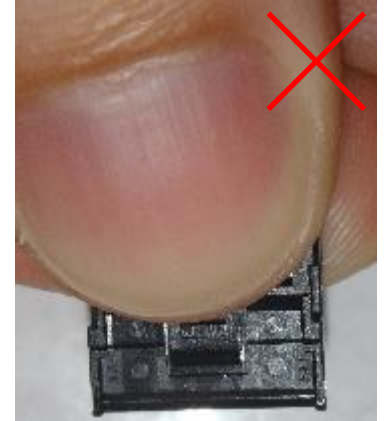
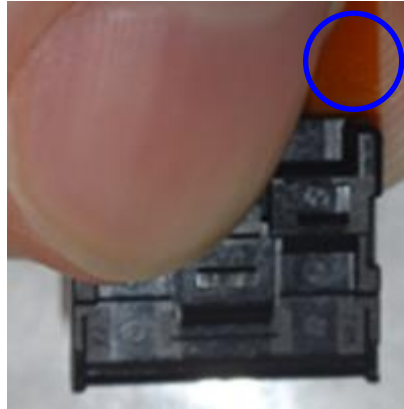


- ・嵌合状態 及び 嵌合時のFPC引き回し作業においてロック部に無理な負荷が掛かるような使用は避けて下さい。  
Please be cautious not to put excess load at the lock part after mating and when FPC is pulled and extracted.

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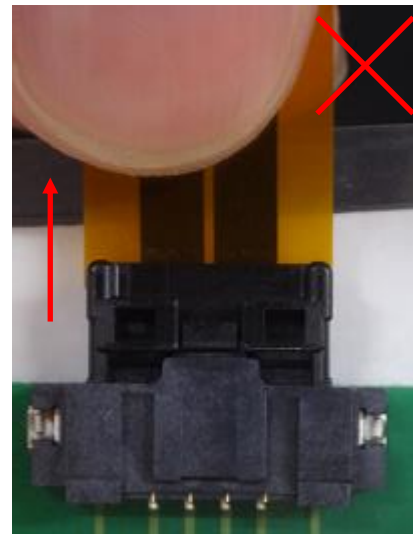
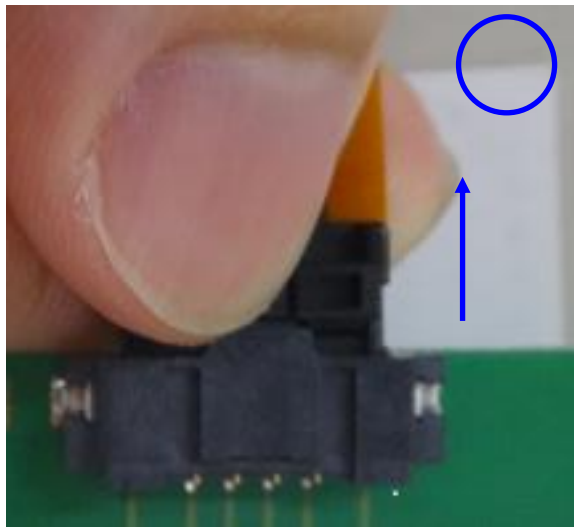
プラグジャケットのロック解除は赤枠の部分のみを押して下さい。プラグジャケット全体を押してしまうとロック解除出来ません。

Please push the red frame area when the plug jacket unlocked. When the whole of the plug jacket is pushed, it is not possible to unlock.



コネクタの嵌合を取り外す際は、必ずロック解除を実施して下さい。

Please be sure to release the lock when unmating the connector.



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**【8. 注意事項 NOTES】**

8-1外観について

8-1-1

本製品の樹脂部に黒点、ウエルド部の線、多少の傷が確認される事がありますが、製品性能には影響ありません。

Although this product may have a small black mark, a weld line or a scratch on the housing, these will not have any influence on the product's performance.

8-1-2

成形品の色相に多少の違いを生じる場合がありますが、製品性能には影響ありません。

There may be slight differences in the housing coloring, but there will be no influence on the product's performance.

8-1-3

紫外線により変色する場合がありますが、製品性能に影響ありません。

Although the ultraviolet light may potentially change the color, this change has no on the product's performance.

8-2実装について

8-2-1

実装性能（平坦度）は、実装基板の反りの影響を含まないものと致します。

基板の反りはコネクタ両端部を基準とし、コネクタ中央部にて Max0.02mmとして下さい。

The mounting specification for coplanarity does not include the influence of warpage of the printed circuit board.

The warpage of the printed circuit board should be a maximum of 0.02mm if measuring from one connector edge to the other.

8-2-2

本製品の一般性能確認はリジット基板にて実施しております。

フレキシブル基板等の特殊な基板へ実装する場合は、事前に実装確認等を行った上でご使用願います。

The product performance was tested using rigid printed circuit board.

In case the product needs to be reflowed onto flexible circuit board, please conduct a reflow test on the flexible circuit board in advance.

8-2-3

フレキシブル基板に実装する場合は、基板の変形を防止するため、補強板をご使用願います。

Please add a stiffener on the flexible printed circuit (FPC) when you mount the connector onto FPC in order to prevent deformation of the FPC.

8-2-4

リフロー条件によっては、樹脂部の変色や端子めっき部にヨリが発生する場合がありますが、製品性能には影響ありません。

Depending on the reflow conditions, there may be the possibility of a color change in the housing.

However, this color change does not have any effect on the product's performance.

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8-2-5

リフロー後、半田付け部に変色が見られることがありますが、製品性能には影響ありません。  
Although there might be some discoloration seen on the soldering tail after reflow, this will not influence the product's performance.

8-2-6

半田実装部の未半田は、ターミナル脱落、ピン間ショート、ターミナル座屈、またコネクタの基板からの外れが懸念されます。従って全てのターミナルテール部及び、ネイル部に半田付けを行って下さい。  
If you leave any soldering area on this product open, there may be the possibility of a missing terminal short circuiting between pins, terminal buckling or the potential for the connector to come off of the printed circuit board. Therefore, please solder all of the terminals and fitting nails on the printed circuit board.

8-2-7

実装機によってコネクタに負荷が加わると変形、破損する場合がありますので事前にご確認下さい。  
If there is accidental contact with the connector while it is going through the reflow machine, there may be deformation or damage caused to the connector. Please check to prevent this.

8-3製品の仕様について

8-3-1

コネクタの性能を損なう恐れがある為、コネクタの洗浄は行わないで下さい。  
Please do not conduct any "washing process" on the connector because it may damage the product's function.

8-3-2

適合するFPCの導体部は、金めっき（ニッケル下地）品をご使用願います。  
Please make sure to use the appropriate FPC which has Gold plating (Nickel under plating) on the contact area.

8-3-3

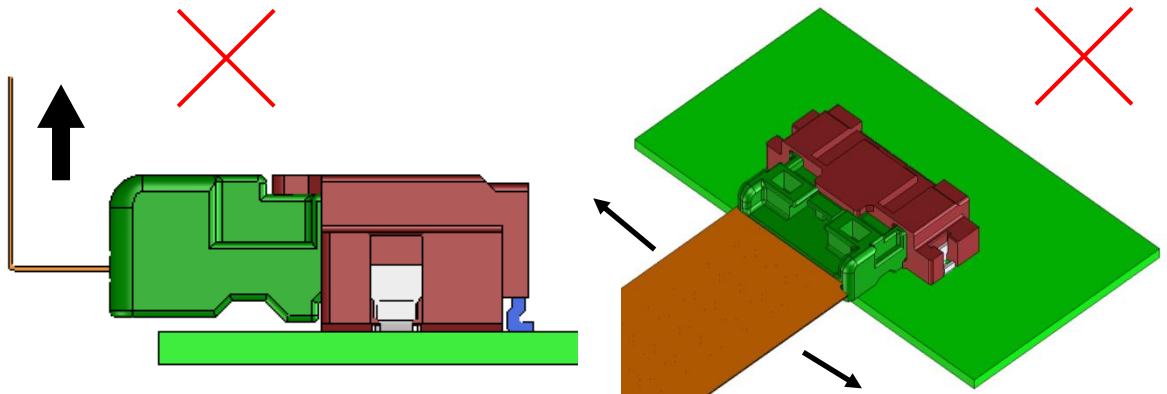
量産前にご使用になるFPCとの相性確認を行った上で、ご使用願います。  
Please check the compatibility between the connector and the FPC prior to moving to mass production.

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8-3-4

コネクタにFPCを嵌合した状態で、FPCに過度の負荷が加わらないようにご注意頂き、御社基板のスペース上、コネクタに負担の掛かる位置への取り付けはしないで下さい。  
 コネクタのロックが解除されたり、FPCの抜け、断線、破損や接触不良の原因になります。  
 特に、連続的に加わる場合はFPCを固定するようにして下さい。  
 また、基板に対して垂直上下方向の引張荷重、コンタクトピッチ方向のこじり荷重を与えない様にご注意願います。  
 Please pay special attention not to have any pulling force/tension on the FPC when it is inserted into the connector. This can cause; the actuator to be unlocked, the actuator to come off, cut the traces on the FPC, and/or damage the FPC.  
 Please be especially careful to avoid placing the FPC in a location where it will have a constant force applied on the FPC, If necessary, please fix the FPC directly on the chassis.  
 Also, please avoid pulling the FPC vertically or twisting the FPC back and force horizontally while it is inserted in the connector.



8-3-5

本製品をご使用時に取り付けられた電線・プリント基板の共振や、機器の回転構造や可動部分の動作によりコネクタ嵌合部（接点部）が常に動いてしまう状態でのご使用は避けて下さい。  
 接触部の摺動磨耗等による 接触不良の原因となります。  
 従って、機器内で電線・プリント基板を固定し、共振を抑える等の処置をお願い致します。  
 Please do not use the connector in a condition where the wire, the printed circuit board, or the contact area is experiencing a sympathetic vibration of wires and printed circuit board, and constant movement of devices. This may cause a defect in the contact due to the contact area being worn down.  
 Therefore, please fix wires and printed circuit board on the chassis, and reduces sympathetic vibration.

8-3-6

活電状態の電気回路で、挿入、抜去ができることを前提に作られていません。スパーク等による危険の発生、性能不良につながりますので、活電状態での挿入、抜去はしないで下さい。  
 This product is not designed for the mating and unmating of the connectors to be performed under the condition of an active electrical circuit. It may cause a spark and product defect if the connectors are mated and unmated in this way.

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8-3-7

コネクタに外力が加わらないようにクリアランスをあげた筐体構造にしてください。

Please keep enough clearance between connector and chassis of your application in order not to apply pressure on the connector.

8-3-8

基板実装後に基板を直接積み重ねない様に注意してください。

Please do not stack the printed circuit board directly after mounted the connector on it.

8-4リペアについて

8-4-1

実装後において半田ごてによる修正を行う際は、必ず仕様書掲載の条件以内で行ってください。

条件を超えて実施した場合、端子の抜け、接点ギャップの変化、モールドの変形、溶融等、破損の原因になります。  
When conducting manual repairs using a soldering iron, please follow the soldering conditions shown in the product specification.

If the conditions in the product spec are not followed, it may cause the terminals to fall off, a change in the contact gap, a deformation of the housing, melting of the housing, and damage the connector.

8-4-2

半田ごてによる修正を行なう際、過度の半田やフラックスを使用しないでください。

半田上がりやフラックス上がりにより接触、機能不良に至る場合があります。

When conducting manual repairs using a soldering iron, please do not use more solder and flux than needed. This may cause solder wicking and flux wicking issues, and it will eventually cause a contact defect and functional issues.

**【9. 環境指令への適合 COMPLIANCE WITH ENVIRONMENTAL DIRECTIVE】**

ELV及びRoHS適合品

ELV and RoHS Compliant.

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